I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted via the Office electronic filling system in accordance with § 1.6(a)(4).

Docket No.: APPM/007385/PPC/ECP/CKIM 1016.012390

(PATENT)

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: 99999 Deenesh Padhi, et al.

Serial No.: 10/678,003

Confirmation No 9225

Filed: October 2, 2003

HOMOGENEOUS COPPER-PALLADIUM ALLOY PLATING FOR ENHANCEMENT OF **FLECTRO-MIGRATION** 

RESISTANCE IN INTERCONNECTS

Group Art Unit: 1753

Examiner: Edna Wong

## AMENDMENT IN RESPONSE TO RESTRICTION REQUIREMENT

š

*9999999999* 

MAIL STOP AMENDMENT Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

For:

## INTRODUCTORY COMMENTS

In response to the Restriction Requirement dated July 9, 2007, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.